

IN THE CLAIMS:

The text of all pending claims, (including withdrawn claims) is set forth below. Cancelled and not entered claims are indicated with claim number and status only. The claims as listed below show added text with underlining and deleted text with ~~strikethrough~~. The status of each claim is indicated with one of (original), (currently amended), (cancelled), (withdrawn), (new), (previously presented), or (not entered).

1. (currently amended) A method of mounting an electronic part, comprising ~~the steps of:~~
applying flux-fill, which acts as flux and under-filling resin, on a surface of a mount board, in which electrodes are formed;
respectively connecting solder ~~bumps~~bumps of the electronic part with the electrodes, the solder bumps being area-arranged on a surface of the electronic part; and
simultaneously filling a gap between the electronic part and the mount board with the flux-fill,
wherein the solder bumps are made contact with the electrodes, and ultrasonic vibration energy is applied to contact portions of the solder bumps and the electrodes in said connecting step.
2. (currently amended) The method according to claim 1,
wherein the electronic part is ultrasonic-vibrated so as to connect the solder ~~bumps~~bumps with the electrodes in said connecting ~~step~~.
3. (original) The method according to claim 1,
wherein the flux-fill includes fillers.
4. (currently amended) The method according to claim 1,
further comprising ~~the step of~~ heating the flux-fill to solidify.
5. (original) The method according to claim 1,
wherein the flux-fill comprises:
a main agent made from resin;
a hardening agent for hardening the resin;
a hardening accelerator;

organic acid acting as flux; and
fillers.

6. (canceled)